

# ESDU6V8HP

## Transient Voltage Suppressors

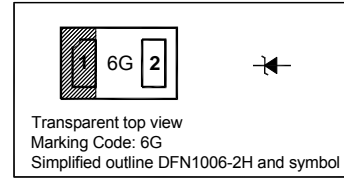
for ESD Protection

### PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode

### Features

- Ultra-Small Leadless Surface Mount Package



### Absolute Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Value	Unit
Peak Pulse Power ( $t_p = 8/20 \mu\text{s}$ ) <sup>1)</sup>	$P_{PK}$	85	W
Peak Pulse Current ( $t_p = 8/20 \mu\text{s}$ ) <sup>1)</sup>	$I_{PP}$	4.5	A
IEC61000-4-2 (ESD) Air Contact	$V_{ESD}$	25 8	KV
Operating Junction and Storage Temperature Range	$T_j, T_{stg}$	- 65 to + 150	$^\circ\text{C}$

### Thermal Characteristics ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Value	Unit
Power Dissipation <sup>1)</sup>	$P_D$	250	mW
Thermal Resistance from Junction to Ambient <sup>1)</sup>	$R_{\theta JA}$	500	$^\circ\text{C/W}$

<sup>1)</sup> Part mounted on FR-4 PC board with recommended pad layout.

### Characteristics at ( $T_a = 25^\circ\text{C}$ )

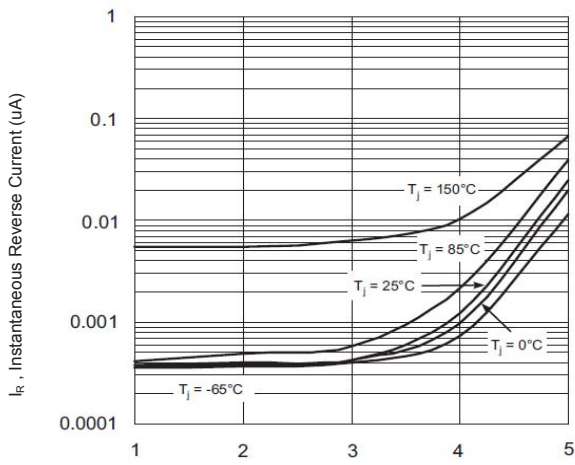
Parameter	Symbol	Min.	Max.	Unit
Reverse Stand-Off Voltage	$V_{RWM}$	-	5	V
Reverse Breakdown Voltage at $I_T = 5 \text{ mA}$	$V_{BR}$	6.4	7.2	V
Forward Voltage at $I_F = 10 \text{ mA}$	$V_F$	-	0.9	V
Reverse Current at $V_{RWM} = 5 \text{ V}$	$I_R$	-	0.5	$\mu\text{A}$
Clamping Voltage at $I_{PP} = 4.5 \text{ A}$ , $t_p = 8/20 \mu\text{s}$	$V_C$	-	19	V
Junction Capacitance at $V_R = 0 \text{ V}$ , $f = 1 \text{ MHz}$	$C_j$	-	65	pF

**TOP DYNAMIC**

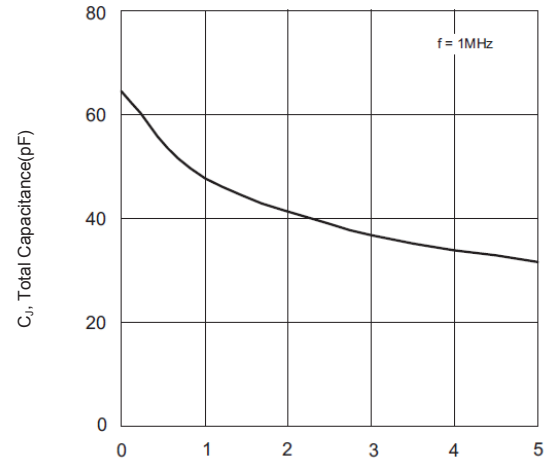


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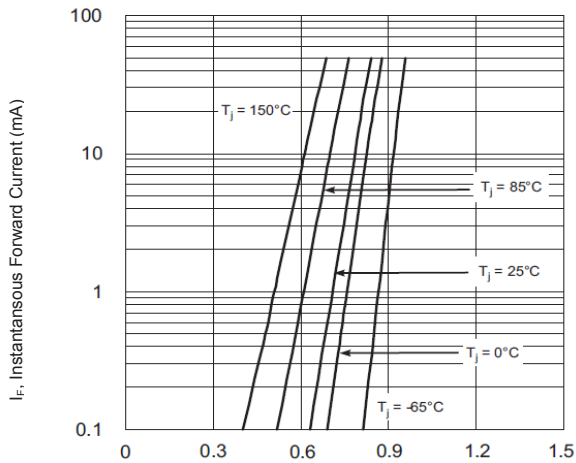
# ESDU6V8HP



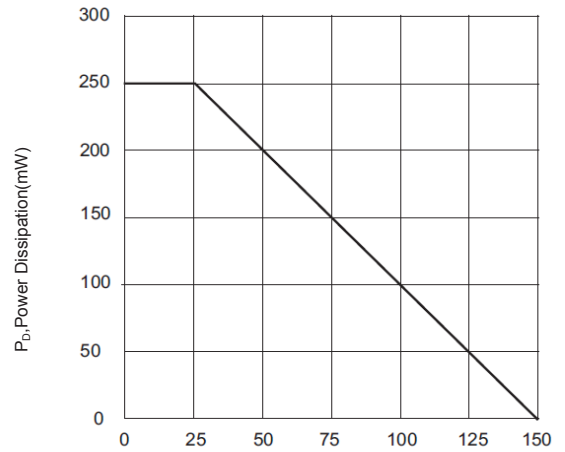
$V_R$ , Instantaneous Reverse Voltage (V)  
Figure. 1 Typical Reverse Characteristics



$V_R$ , Reverse Voltage (V)  
Figure. 2 Typical Total Capacitance



$V_F$ , Instantaneous Forward Voltage(V)  
Figure. 3 Typical Forward Characteristics



$T_A$ , Ambient Temperature (°C)  
Figure.4 Power Derating Curve

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ISO14001 : 2004 Certificate No. 121505007    ISO 9001 : 2008 Certificate No. 50114012    OHSAS 18001 : 2007 Certificate No. 0513150808    IECQ QC 080000 Certificate No. 8241800741M2

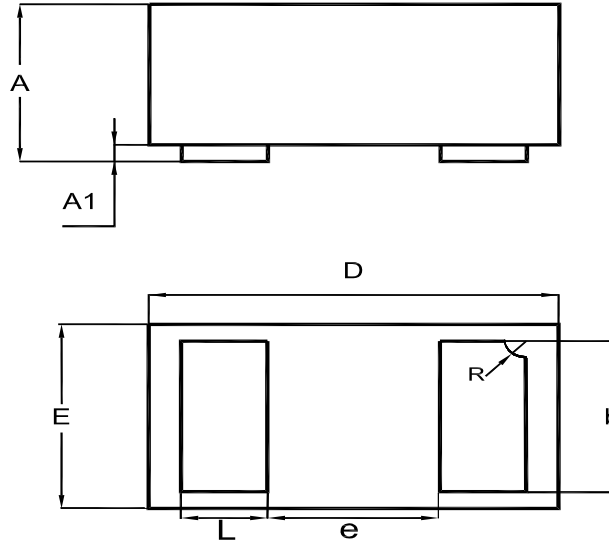
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## PACKAGE OUTLINE

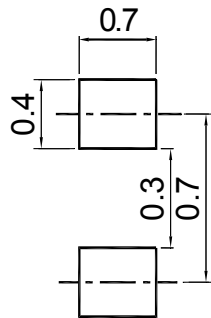
Plastic surface mounted package

DFN1006-2H



UNIT	A	A1	b	D	E	e	L	R
mm	0.51 0.46	0.05 0	0.55 0.45	1.05 0.95	0.65 0.55	0.4	0.3 0.2	0.15 0.05

## Recommended Soldering Footprint



## Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
DFN1006-2H	8	4 ± 0.1	0.157 ± 0.004	178	7	5,000

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